

IN THE SPECIFICATION

Please replace the subparagraph at page 20, line 1, with the following subparagraph:

115 DC ~~current~~ power source

Please replace the paragraph beginning at page 52, line 26, through page 53, line 11 with the following rewritten paragraph:

The sheet-like connector 48 in the contact member 45 is formed by arranging contacts 49 composed of a metallic body and each extending through an insulating sheet 48a in a thickness-wise direction in the insulating sheet 48a. The contacts 49 in the sheet-like connector 48 is each formed by a semi-spherical front-surface electrode 49a exposed to a front surface of the insulating sheet 48a, a flat back-surface electrode 49b exposed to a back surface of the insulating sheet 48a and a short circuit part 49c extending through in the thickness-wise direction of the insulating sheet 48a and linking the front-surface electrode 49a and the back-surface electrode ~~[[48b]]~~ 49b to each other.

Please replace the paragraph beginning at page 53, line 24, through page 54, line 8, with the following rewritten paragraph:

In the wafer inspection apparatus described above, the wafer 1 that is the object of inspection is mounted on the wafer tray 36, and the circuit board 30 for inspection is pressurized downward by the pressurizing mechanism ~~[[36]]~~ 35, whereby the contacts of the contact member 45 come into contact with respective electrodes to be inspected of a part of the integrated circuits formed on the wafer 1, thereby achieving necessary electrical connection. The wafer 1 is then heated to a predetermined temperature by the wafer tray 36 to perform necessary electrical inspection (WLBI test or probe test) as to the wafer 1 in this state.

Please replace the paragraph at page 54, lines 9-12, with the following rewritten paragraph:

In the above-described process, the pressurizing force by the pressurizing mechanism [[36]] 35 is selected from a range in which a stable electrical connection of the contact member 45 to the wafer 1 is achieved.

Please replace the paragraph beginning at page 58, line 17, through page 59, line 5, with the following rewritten paragraph:

In such a wafer inspection apparatus, the circuit board 30 for inspection is pressurized downward by the pressurizing mechanism [[36]] 35, whereby the conductive parts 16 for connection in the anisotropically conductive connector 10 are pressurized in the thickness-wise direction, thereby electrically connecting the inspection electrodes 31 of the circuit board 30 for inspection to their corresponding terminal electrodes 42 of the circuit board 41 for connection, and bringing the respective contacts of the contact member 45 into contact with electrodes to be inspected of a part of integrated circuits formed on a wafer 1. Necessary electrical connection is thereby achieved. The wafer 1 is then heated to a predetermined temperature by the wafer tray 36 to perform necessary electrical inspection (WLBI test or probe test) as to the wafer 1 in this state.